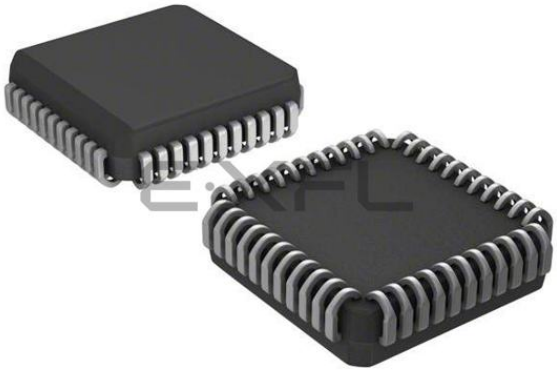

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	4KB (2K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	232 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c42at-16i-l

2.0 PIC17C4X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC17C4X Product Selection System section at the end of this data sheet. When placing orders, please use the "PIC17C4X Product Identification System" at the back of this data sheet to specify the correct part number.

For the PIC17C4X family of devices, there are four device "types" as indicated in the device number:

1. **C**, as in PIC17**C**42. These devices have EPROM type memory and operate over the standard voltage range.
2. **LC**, as in PIC17**LC**42. These devices have EPROM type memory, operate over an extended voltage range, and reduced frequency range.
3. **CR**, as in PIC17**CR**42. These devices have ROM type memory and operate over the standard voltage range.
4. **LCR**, as in PIC17**LCR**42. These devices have ROM type memory, operate over an extended voltage range, and reduced frequency range.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs.

The UV erasable version can be erased and reprogrammed to any of the configuration modes. Microchip's PRO MATE™ programmer supports programming of the PIC17C4X. Third party programmers also are available; refer to the *Third Party Guide* for a list of sources.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround Production (SQTP^{SM}) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

ROM devices do not allow serialization information in the program memory space.

For information on submitting ROM code, please contact your regional sales office.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, thus giving customers a low cost option for high volume, mature products.

For information on submitting ROM code, please contact your regional sales office.

FIGURE 4-2: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD})

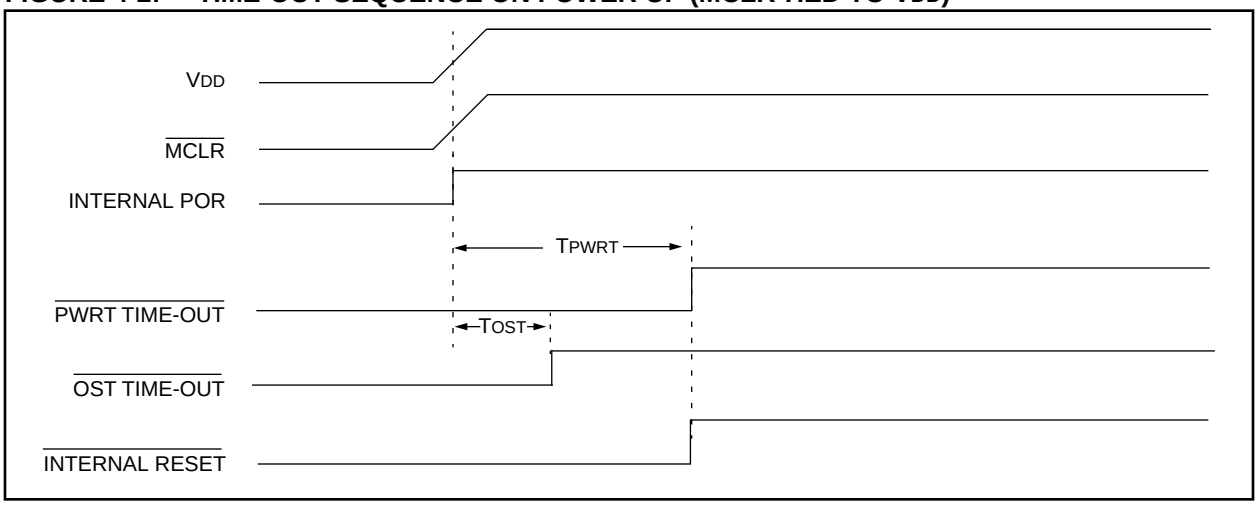


FIGURE 4-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD})

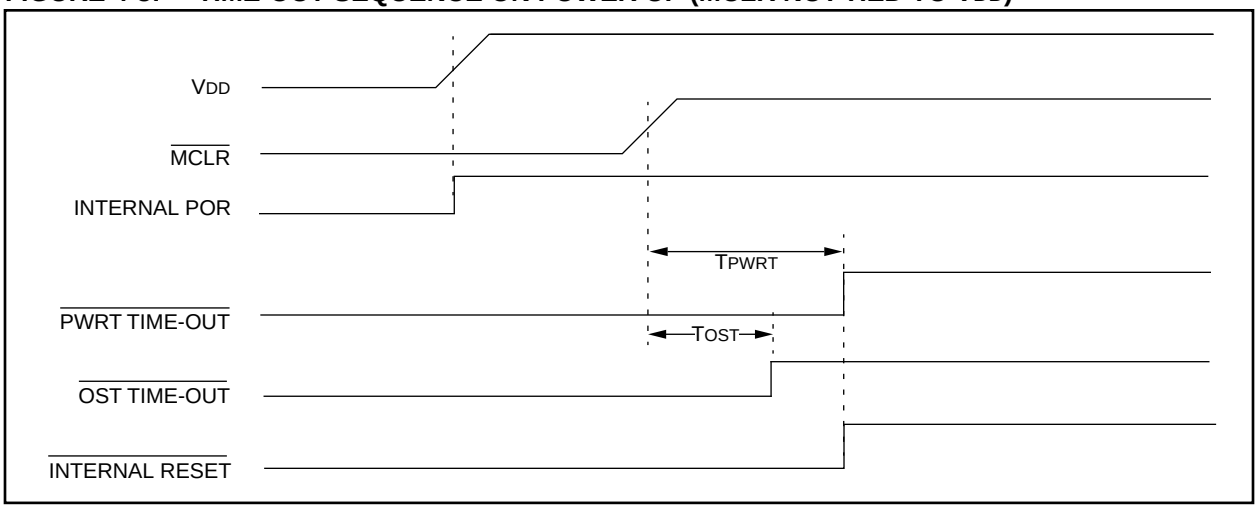


FIGURE 4-4: SLOW RISE TIME ($\overline{MCLR}$ TIED TO V_{DD})

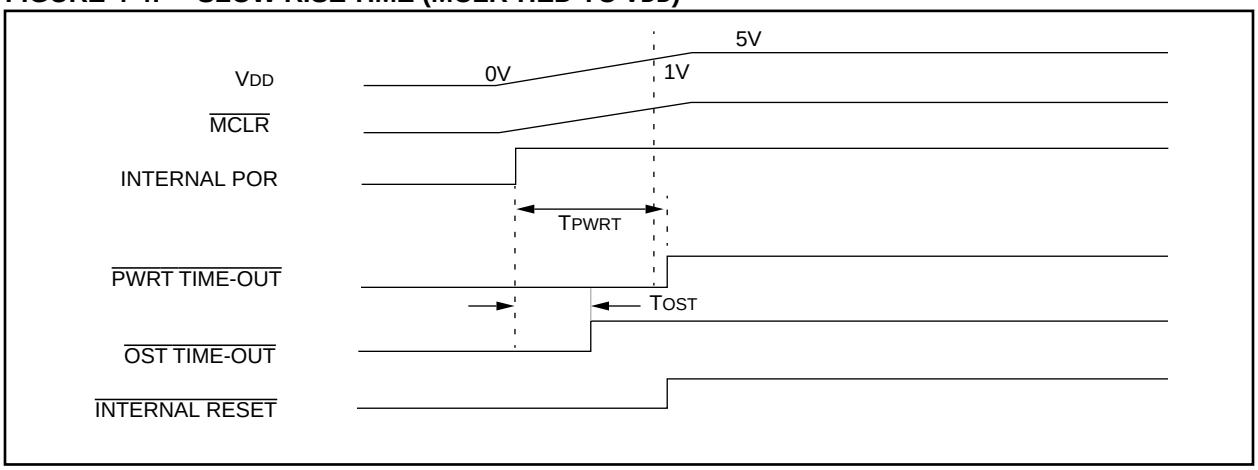
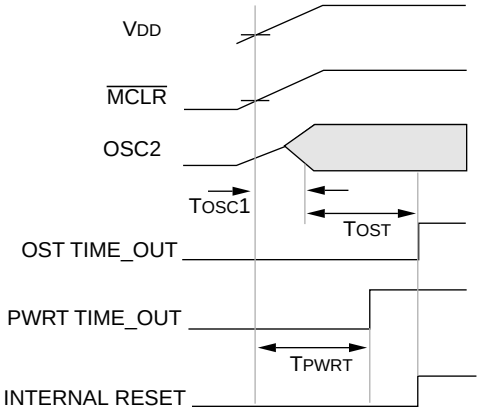


FIGURE 4-5: OSCILLATOR START-UPTIME



This figure shows in greater detail the timings involved with the oscillator start-up timer. In this example the low frequency crystal start-up time is larger than power-up time (TPWRT).
Tosc1 = time for the crystal oscillator to react to an oscillation level detectable by the Oscillator Start-up Timer (ost).
TOST = 1024TOSC.

FIGURE 4-6: USING ON-CHIP POR

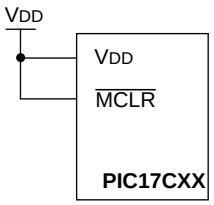
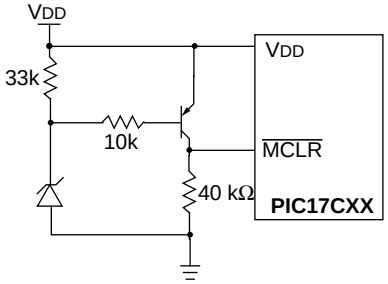
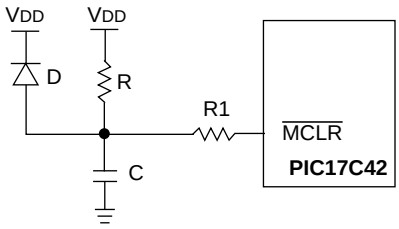


FIGURE 4-7: BROWN-OUT PROTECTION CIRCUIT 1



This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

FIGURE 4-8: PIC17C42 EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

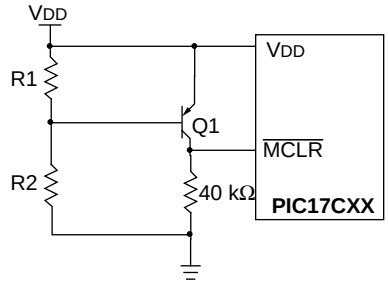


Note 1: An external Power-on Reset circuit is required only if VDD power-up time is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to ensure that the voltage drop across R does not exceed 0.2V (max. leakage current spec. on the MCLR/VPP pin is 5 μA). A larger voltage drop will degrade VIH level on the MCLR/VPP pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or (Electrical Overstress) EOS.

FIGURE 4-9: BROWN-OUT PROTECTION CIRCUIT 2



This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

5.0 INTERRUPTS

The PIC17C4X devices have 11 sources of interrupt:

- External interrupt from the RA0/INT pin
- Change on RB7:RB0 pins
- TMR0 Overflow
- TMR1 Overflow
- TMR2 Overflow
- TMR3 Overflow
- USART Transmit buffer empty
- USART Receive buffer full
- Capture1
- Capture2
- T0CKI edge occurred

There are four registers used in the control and status of interrupts. These are:

- CPUSTA
- INTSTA
- PIE
- PIR

The CPUSTA register contains the GLINTD bit. This is the Global Interrupt Disable bit. When this bit is set, all interrupts are disabled. This bit is part of the controller core functionality and is described in the Memory Organization section.

When an interrupt is responded to, the GLINTD bit is automatically set to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with the interrupt vector address. There are four interrupt vectors. Each vector address is for a specific interrupt source (except the peripheral interrupts which have the same vector address). These sources are:

- External interrupt from the RA0/INT pin
- TMR0 Overflow
- T0CKI edge occurred
- Any peripheral interrupt

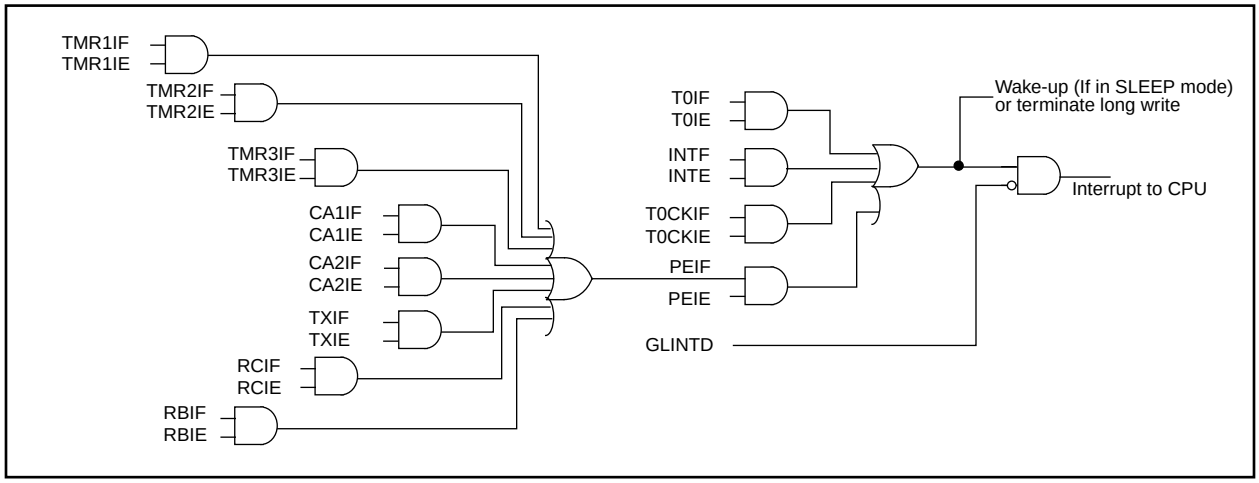
When program execution vectors to one of these interrupt vector addresses (except for the peripheral interrupt address), the interrupt flag bit is automatically cleared. Vectoring to the peripheral interrupt vector address does not automatically clear the source of the interrupt. In the peripheral interrupt service routine, the source(s) of the interrupt can be determined by testing the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests.

All of the individual interrupt flag bits will be set regardless of the status of their corresponding mask bit or the GLINTD bit.

For external interrupt events, there will be an interrupt latency. For two cycle instructions, the latency could be one instruction cycle longer.

The “return from interrupt” instruction, `RETFIE`, can be used to mark the end of the interrupt service routine. When this instruction is executed, the stack is “POPed”, and the GLINTD bit is cleared (to re-enable interrupts).

FIGURE 5-1: INTERRUPT LOGIC



6.2 Data Memory Organization

Data memory is partitioned into two areas. The first is the General Purpose Registers (GPR) area, while the second is the Special Function Registers (SFR) area. The SFRs control the operation of the device.

Portions of data memory are banked, this is for both areas. The GPR area is banked to allow greater than 232 bytes of general purpose RAM. SFRs are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the Bank Select Register (BSR). If an access is made to a location outside this banked region, the BSR bits are ignored. Figure 6-5 shows the data memory map organization for the PIC17C42 and Figure 6-6 for all of the other PIC17C4X devices.

Instructions MOVPF and MOVFP provide the means to move values from the peripheral area (“P”) to any location in the register file (“F”), and vice-versa. The definition of the “P” range is from 0h to 1Fh, while the “F” range is 0h to FFh. The “P” range has six more locations than peripheral registers (eight locations for the PIC17C42 device) which can be used as General Purpose Registers. This can be useful in some applications where variables need to be copied to other locations in the general purpose RAM (such as saving status information during an interrupt).

The entire data memory can be accessed either directly or indirectly through file select registers FSR0 and FSR1 (Section 6.4). Indirect addressing uses the appropriate control bits of the BSR for accesses into the banked areas of data memory. The BSR is explained in greater detail in Section 6.8.

6.2.1 GENERAL PURPOSE REGISTER (GPR)

All devices have some amount of GPR area. The GPRs are 8-bits wide. When the GPR area is greater than 232, it must be banked to allow access to the additional memory space.

Only the PIC17C43 and PIC17C44 devices have banked memory in the GPR area. To facilitate switching between these banks, the MOVLR bank instruction has been added to the instruction set. GPRs are not initialized by a Power-on Reset and are unchanged on all other resets.

6.2.2 SPECIAL FUNCTION REGISTERS (SFR)

The SFRs are used by the CPU and peripheral functions to control the operation of the device (Figure 6-5 and Figure 6-6). These registers are static RAM.

The SFRs can be classified into two sets, those associated with the “core” function and those related to the peripheral functions. Those registers related to the “core” are described here, while those related to a peripheral feature are described in the section for each peripheral feature.

The peripheral registers are in the banked portion of memory, while the core registers are in the unbanked region. To facilitate switching between the peripheral banks, the MOVLB bank instruction has been provided.

6.8 Bank Select Register (BSR)

The BSR is used to switch between banks in the data memory area (Figure 6-13). In the PIC17C42, PIC17CR42, and PIC17C42A only the lower nibble is implemented. While in the PIC17C43, PIC17CR43, and PIC17C44 devices, the entire byte is implemented. The lower nibble is used to select the peripheral register bank. The upper nibble is used to select the general purpose memory bank.

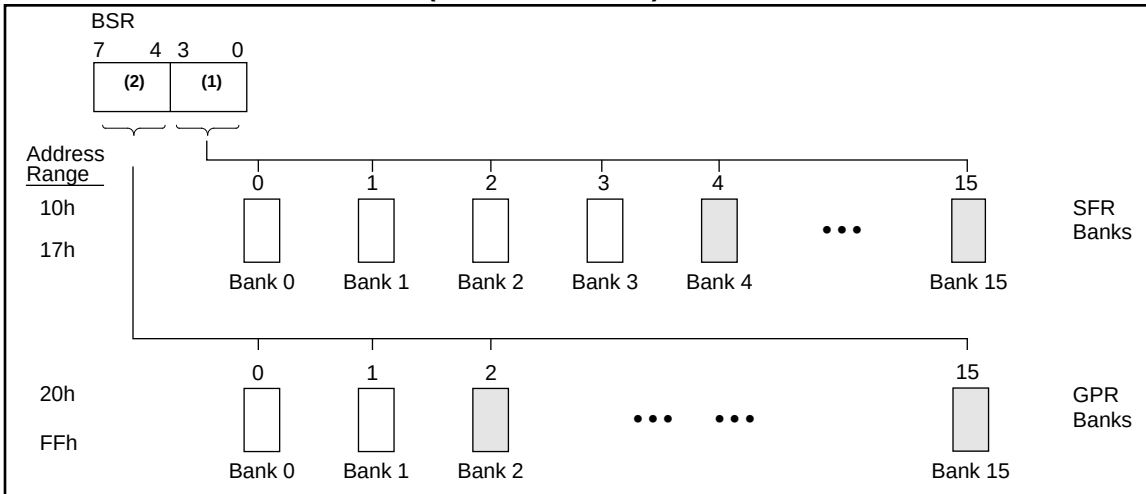
All the Special Function Registers (SFRs) are mapped into the data memory space. In order to accommodate the large number of registers, a banking scheme has been used. A segment of the SFRs, from address 10h to address 17h, is banked. The lower nibble of the bank select register (BSR) selects the currently active "peripheral bank." Effort has been made to group the peripheral registers of related functionality in one bank. However, it will still be necessary to switch from bank to bank in order to address all peripherals related to a single task. To assist this, a `MOVLB bank` instruction is in the instruction set.

For the PIC17C43, PIC17CR43, and PIC17C44 devices, the need for a large general purpose memory space dictated a general purpose RAM banking scheme. The upper nibble of the BSR selects the currently active general purpose RAM bank. To assist this, a `MOVLR bank` instruction has been provided in the instruction set.

If the currently selected bank is not implemented (such as Bank 13), any read will read all '0's. Any write is completed to the bit bucket and the ALU status bits will be set/cleared as appropriate.

Note:	Registers in Bank 15 in the Special Function Register area, are reserved for Microchip use. Reading of registers in this bank may cause random values to be read.

FIGURE 6-13: BSR OPERATION (PIC17C43/R43/44)



Note 1: Only Banks 0 through Bank 3 are implemented. Selection of an unimplemented bank is not recommended**.**
Bank 15 is reserved for Microchip use, reading of registers in this bank may cause random values to be read.
2: Only Banks 0 and Bank 1 are implemented. Selection of an unimplemented bank is not recommended.

9.4 PORTD and DDRD Registers

PORTD is an 8-bit bi-directional port. The corresponding data direction register is DDRD. A '1' in DDRD configures the corresponding port pin as an input. A '0' in the DDRC register configures the corresponding port pin as an output. Reading PORTD reads the status of the pins, whereas writing to it will write to the port latch. PORTD is multiplexed with the system bus. When operating as the system bus, PORTD is the high order byte of the address/data bus (AD15:AD8). The timing for the system bus is shown in the Electrical Characteristics section.

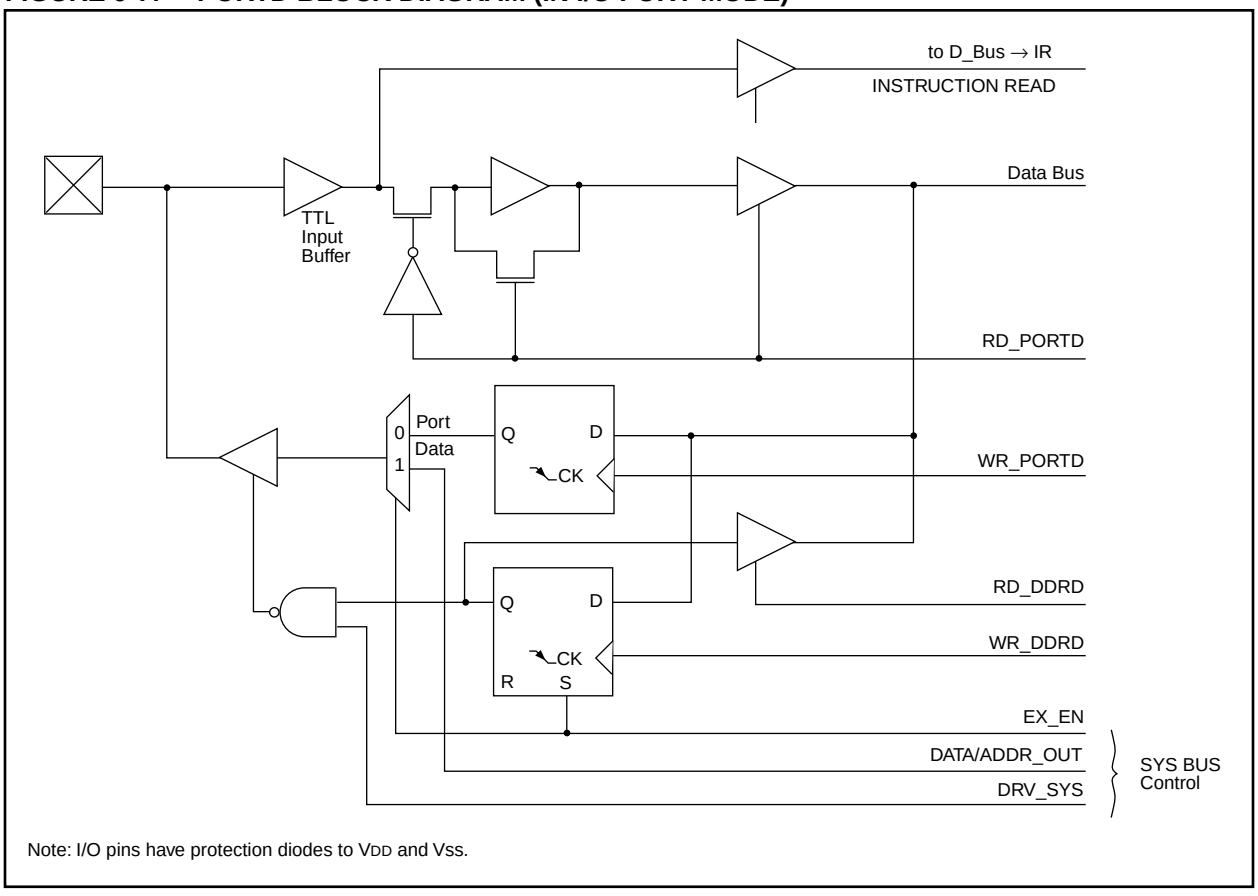
Note:	This port is configured as the system bus when the device's configuration bits are selected to Microprocessor or Extended Microcontroller modes. In the two other microcontroller modes, this port is a general purpose I/O.

Example 9-3 shows the instruction sequence to initialize PORTD. The Bank Select Register (BSR) must be selected to Bank 1 for the port to be initialized.

EXAMPLE 9-3: INITIALIZING PORTD

```
MOVLB  1          ;  Select Bank 1
CLRF   PORTD      ;  Initialize PORTD data
                  ;   latches before setting
                  ;   the data direction
                  ;   register
MOVLW  0xCF       ;  Value used to initialize
                  ;   data direction
MOVWF  DDRD       ;  Set RD<3:0> as inputs
                  ;   RD<5:4> as outputs
                  ;   RD<7:6> as inputs
```

FIGURE 9-7: PORTD BLOCK DIAGRAM (IN I/O PORT MODE)



Note: I/O pins have protection diodes to VDD and Vss.

12.1.3 USING PULSE WIDTH MODULATION (PWM) OUTPUTS WITH TMR1 AND TMR2

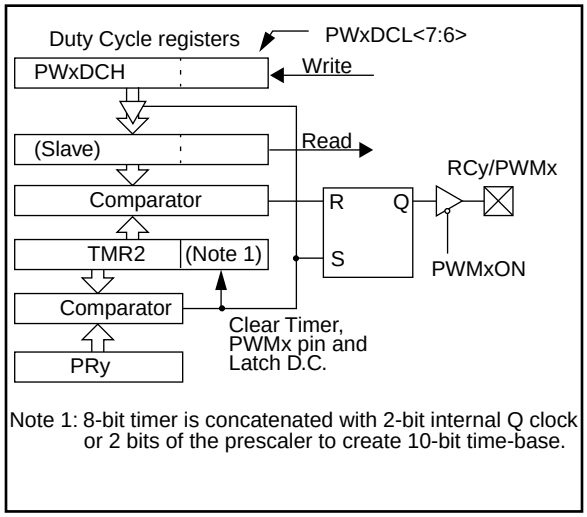
Two high speed pulse width modulation (PWM) outputs are provided. The PWM1 output uses Timer1 as its time-base, while PWM2 may be software configured to use either Timer1 or Timer2 as the time-base. The PWM outputs are on the RB2/PWM1 and RB3/PWM2 pins.

Each PWM output has a maximum resolution of 10-bits. At 10-bit resolution, the PWM output frequency is 24.4 kHz (@ 25 MHz clock) and at 8-bit resolution the PWM output frequency is 97.7 kHz. The duty cycle of the output can vary from 0% to 100%.

Figure 12-5 shows a simplified block diagram of the PWM module. The duty cycle register is double buffered for glitch free operation. Figure 12-6 shows how a glitch could occur if the duty cycle registers were not double buffered.

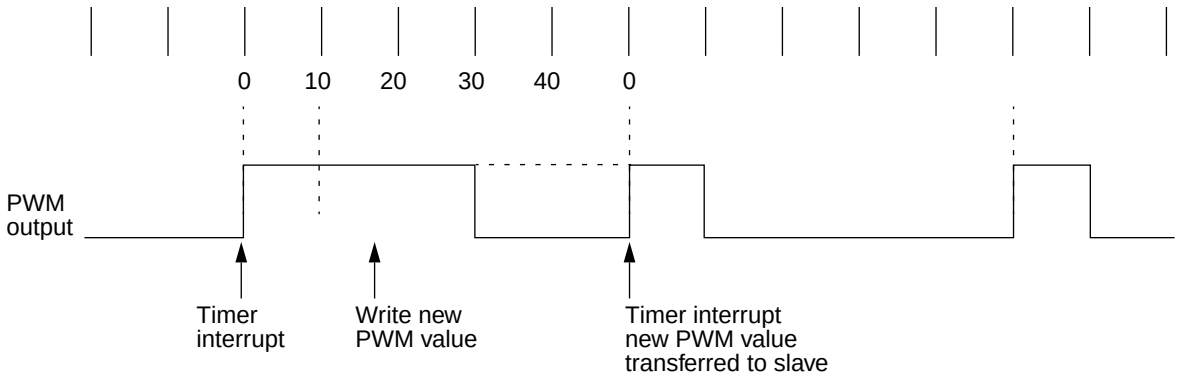
The user needs to set the PWM1ON bit (TCON2<4>) to enable the PWM1 output. When the PWM1ON bit is set, the RB2/PWM1 pin is configured as PWM1 output and forced as an output irrespective of the data direction bit (DDRB<2>). When the PWM1ON bit is clear, the pin behaves as a port pin and its direction is controlled by its data direction bit (DDRB<2>). Similarly, the PWM2ON (TCON2<5>) bit controls the configuration of the RB3/PWM2 pin.

FIGURE 12-5: SIMPLIFIED PWM BLOCK DIAGRAM



Note 1: 8-bit timer is concatenated with 2-bit internal Q clock or 2 bits of the prescaler to create 10-bit time-base.

FIGURE 12-6: PWM OUTPUT



Note The dotted line shows PWM output if duty cycle registers were not double buffered. If the new duty cycle is written after the timer has passed that value, then the PWM does not reset at all during the current cycle causing a “glitch”.

In this example, PWM period = 50. Old duty cycle is 30. New duty cycle value is 10.

MOVLR **Move Literal to high nibble in BSR**

Syntax: [*label*] MOVLR k

Operands: $0 \le k \le 15$

Operation: k → (BSR<7:4>)

Status Affected: None

Encoding:

1011	101x	kkkk	uuuu

Description: The 4-bit literal 'k' is loaded into the most significant 4-bits of the Bank Select Register (BSR). Only the high 4-bits of the Bank Select Register are affected. The lower half of the BSR is unchanged. The assembler will encode the “u” fields as 0.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k:u'	Execute	Write literal 'k' to BSR<7:4>

Example: MOVLR 5

Before Instruction
BSR register = 0x22

After Instruction
BSR register = 0x52

Note: This instruction is not available in the PIC17C42 device.

MOVLW **Move Literal to WREG**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: k → (WREG)

Status Affected: None

Encoding:

1011	0000	kkkk	kkkk

Description: The eight bit literal 'k' is loaded into WREG.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write to WREG

Example: MOVLW 0x5A

After Instruction
WREG = 0x5A

MULLW **Multiply Literal with WREG**

Syntax: [*label*] MULLW k

Operands: $0 \le k \le 255$

Operation: (k x WREG) → PRODH:PRODL

Status Affected: None

Encoding:

1011	1100	kkkk	kkkk

Description: An unsigned multiplication is carried out between the contents of WREG and the 8-bit literal 'k'. The 16-bit result is placed in PRODH:PRODL register pair. PRODH contains the high byte.
WREG is unchanged.
None of the status flags are affected.
Note that neither overflow nor carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write registers PRODH: PRODL

Example: `MULLW 0xC4`

Before Instruction
WREG = 0xE2
PRODH = ?
PRODL = ?

After Instruction
WREG = 0xC4
PRODH = 0xAD
PRODL = 0x08

Note: This instruction is not available in the PIC17C42 device.

MULWF **Multiply WREG with f**

Syntax: [*label*] MULWF f

Operands: $0 \le f \le 255$

Operation: (WREG x f) → PRODH:PRODL

Status Affected: None

Encoding:

0011	0100	ffff	ffff

Description: An unsigned multiplication is carried out between the contents of WREG and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte.
Both WREG and 'f' are unchanged.
None of the status flags are affected.
Note that neither overflow nor carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write registers PRODH: PRODL

Example: `MULWF REG`

Before Instruction
WREG = 0xC4
REG = 0xB5
PRODH = ?
PRODL = ?

After Instruction
WREG = 0xC4
REG = 0xB5
PRODH = 0x8A
PRODL = 0x94

Note: This instruction is not available in the PIC17C42 device.

RLNCF **Rotate Left f (no carry)**

Syntax: [*label*] RLNCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

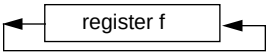
Operation: f<n> → d<n+1>;
f<7> → d<0>

Status Affected: None

Encoding:

0010	001d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RLNCF REG, 1

Before Instruction
C = 0
REG = 1110 1011

After Instruction
C =
REG = 1101 0111

RRCF **Rotate Right f through Carry**

Syntax: [*label*] RRCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

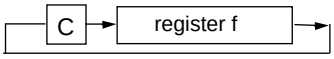
Operation: f<n> → d<n-1>;
f<0> → C;
C → d<7>

Status Affected: C

Encoding:

0001	100d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RRCF REG1,0

Before Instruction
REG1 = 1110 0110
C = 0

After Instruction
REG1 = 1110 0110
WREG = 0111 0011
C = 0

TABLRD **Table Read**

Example1: `TABLRD 1, 1, REG ;`

Before Instruction

REG	=	0x53
TBLATH	=	0xAA
TBLATL	=	0x55
TBLPTR	=	0xA356
MEMORY(TBLPTR)	=	0x1234

After Instruction (table write completion)

REG	=	0xAA
TBLATH	=	0x12
TBLATL	=	0x34
TBLPTR	=	0xA357
MEMORY(TBLPTR)	=	0x5678

Example2: `TABLRD 0, 0, REG ;`

Before Instruction

REG	=	0x53
TBLATH	=	0xAA
TBLATL	=	0x55
TBLPTR	=	0xA356
MEMORY(TBLPTR)	=	0x1234

After Instruction (table write completion)

REG	=	0x55
TBLATH	=	0x12
TBLATL	=	0x34
TBLPTR	=	0xA356
MEMORY(TBLPTR)	=	0x1234

TABLWT **Table Write**

Syntax: [*label*] TABLWT t,i,f

Operands: $0 \le f \le 255$
$i \in [0,1]$
$t \in [0,1]$

Operation: If t = 0,
f → TBLATL;
If t = 1,
f → TBLATH;
TBLAT → Prog Mem (TBLPTR);
If i = 1,
TBLPTR + 1 → TBLPTR

Status Affected: None

Encoding:

1010	11ti	ffff	ffff

Description:

1. Load value in 'f' into 16-bit table latch (TBLAT)
   If t = 0: load into low byte;
   If t = 1: load into high byte
2. The contents of TBLAT is written to the program memory location pointed to by TBLPTR
   If TBLPTR points to external program memory location, then the instruction takes two-cycle
   If TBLPTR points to an internal EPROM location, then the instruction is terminated when an interrupt is received.

Note: The $\overline{MCLR}/V_{PP}$ pin must be at the programming voltage for successful programming of internal memory.
If $\overline{MCLR}/V_{PP} = V_{DD}$
the programming sequence of internal memory will be executed, but will not be successful (although the internal memory location may be disturbed)

3. The TBLPTR can be automatically incremented
   If i = 0; TBLPTR is not incremented
   If i = 1; TBLPTR is incremented

Words: 1

Cycles: 2 (many if write is to on-chip EPROM program memory)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register TBLATH or TBLATL

Applicable Devices	42	R42	42A	43	R43	44

17.0 PIC17C42 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125˚C

Storage temperature ..... -65˚C to +150˚C

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V

Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +12V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V

Total power dissipation (Note 1) 1.0W

Maximum current out of V_{SS} pin(s) - Total ..... 250 mA

Maximum current into V_{DD} pin(s) - Total ..... 200 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA

Maximum output current sunk by RA2 or RA3 pins ..... 60 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA

Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA

Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA

Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-4: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

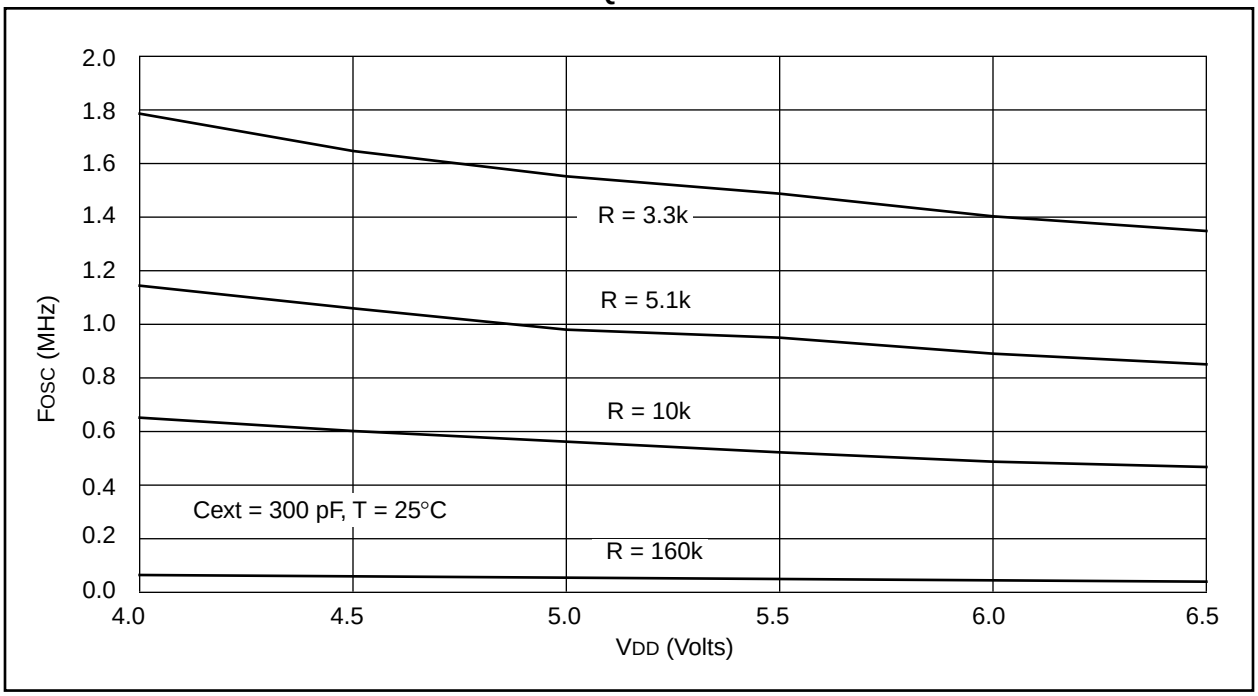


TABLE 18-2: RC OSCILLATOR FREQUENCIES

Cext	Rext	Average Fosc @ 5V, 25°C	
22 pF	10k	3.33 MHz	± 12%
	100k	353 kHz	± 13%
100 pF	3.3k	3.54 MHz	± 10%
	5.1k	2.43 MHz	± 14%
	10k	1.30 MHz	± 17%
	100k	129 kHz	± 10%
300 pF	3.3k	1.54 MHz	± 14%
	5.1k	980 kHz	± 12%
	10k	564 kHz	± 16%
	160k	35 kHz	± 18%

Applicable Devices	42	R42	42A	43	R43	44

TABLE 19-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC17LCR42-08 PIC17LC42A-08 PIC17LC43-08 PIC17LCR43-08 PIC17LC44-08	PIC17CR42-16 PIC17C42A-16 PIC17C43-16 PIC17CR43-16 PIC17C44-16	PIC17CR42-25 PIC17C42A-25 PIC17C43-25 PIC17CR43-25 PIC17C44-25	PIC17CR42-33 PIC17C42A-33 PIC17C43-33 PIC17CR43-33 PIC17C44-33	JW Devices (Ceramic Windowed Devices)
RC	VDD: 2.5V to 6.0V IDD: 6 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 4 MHz max.	VDD: 4.5V to 6.0V IDD: 6 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 4 MHz max.	VDD: 4.5V to 6.0V IDD: 6 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 4 MHz max.	VDD: 4.5V to 6.0V IDD: 6 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 4 MHz max.	VDD: 4.5V to 6.0V IDD: 6 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 4 MHz max.
XT	VDD: 2.5V to 6.0V IDD: 12 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 8 MHz max.	VDD: 4.5V to 6.0V IDD: 24 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 16 MHz max.	VDD: 4.5V to 6.0V IDD: 38 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 25 MHz max.	VDD: 4.5V to 6.0V IDD: 38 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 33 MHz max.	VDD: 4.5V to 6.0V IDD: 38 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 33 MHz max.
EC	VDD: 2.5V to 6.0V IDD: 12 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 8 MHz max.	VDD: 4.5V to 6.0V IDD: 24 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 16 MHz Max	VDD: 4.5V to 6.0V IDD: 38 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 25 MHz max.	VDD: 4.5V to 6.0V IDD: 38 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 33 MHz max.	VDD: 4.5V to 6.0V IDD: 38 mA max. IPD: 5 µA max. at 5.5V WDT disabled Freq: 33 MHz max.
LF	VDD: 2.5V to 6.0V IDD: 150 µA max. at 32 kHz IPD: 5 µA max. at 5.5V WDT disabled Freq: 2 MHz max.	VDD: 4.5V to 6.0V IDD: 95 µA typ. at 32 kHz IPD: < 1 µA typ. at 5.5V WDT disabled Freq: 2 MHz max.	VDD: 4.5V to 6.0V IDD: 95 µA typ. at 32 kHz IPD: < 1 µA typ. at 5.5V WDT disabled Freq: 2 MHz max.	VDD: 4.5V to 6.0V IDD: 95 µA typ. at 32 kHz IPD: < 1 µA typ. at 5.5V WDT disabled Freq: 2 MHz max.	VDD: 2.5V to 6.0V IDD: 150 µA max. at 32 kHz IPD: 5 µA max. at 5.5V WDT disabled Freq: 2 MHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

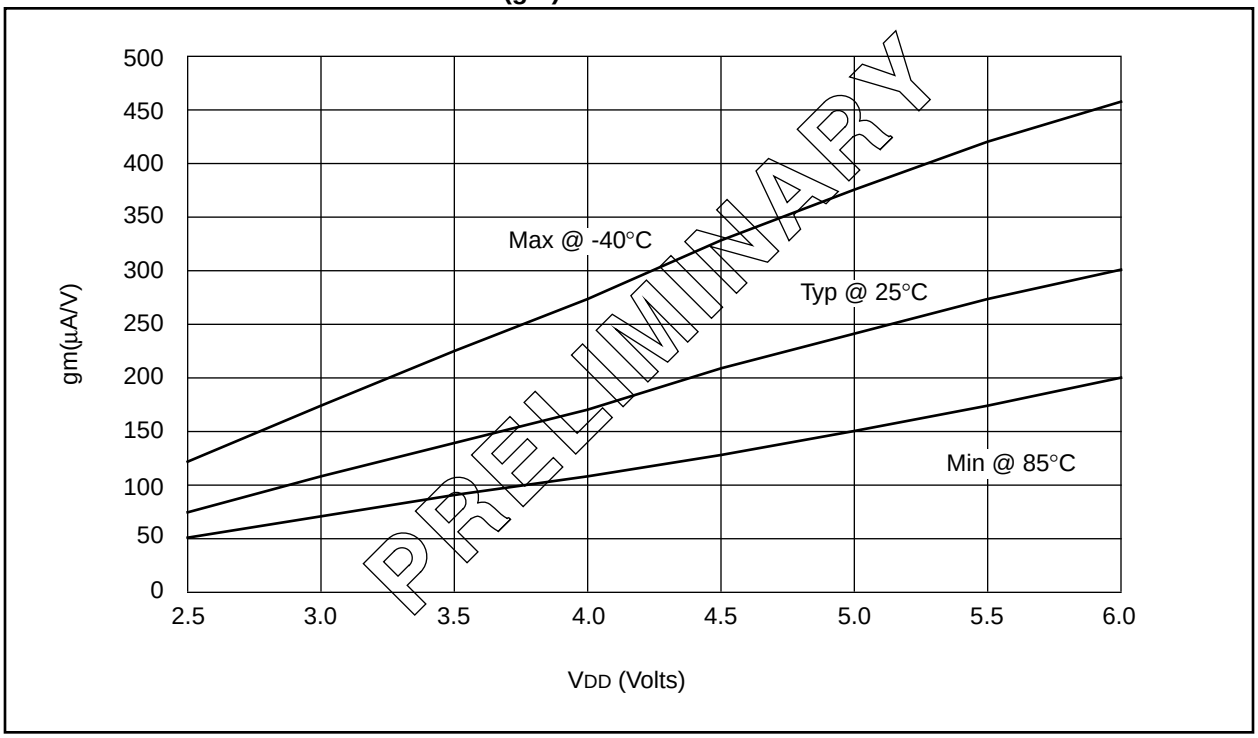
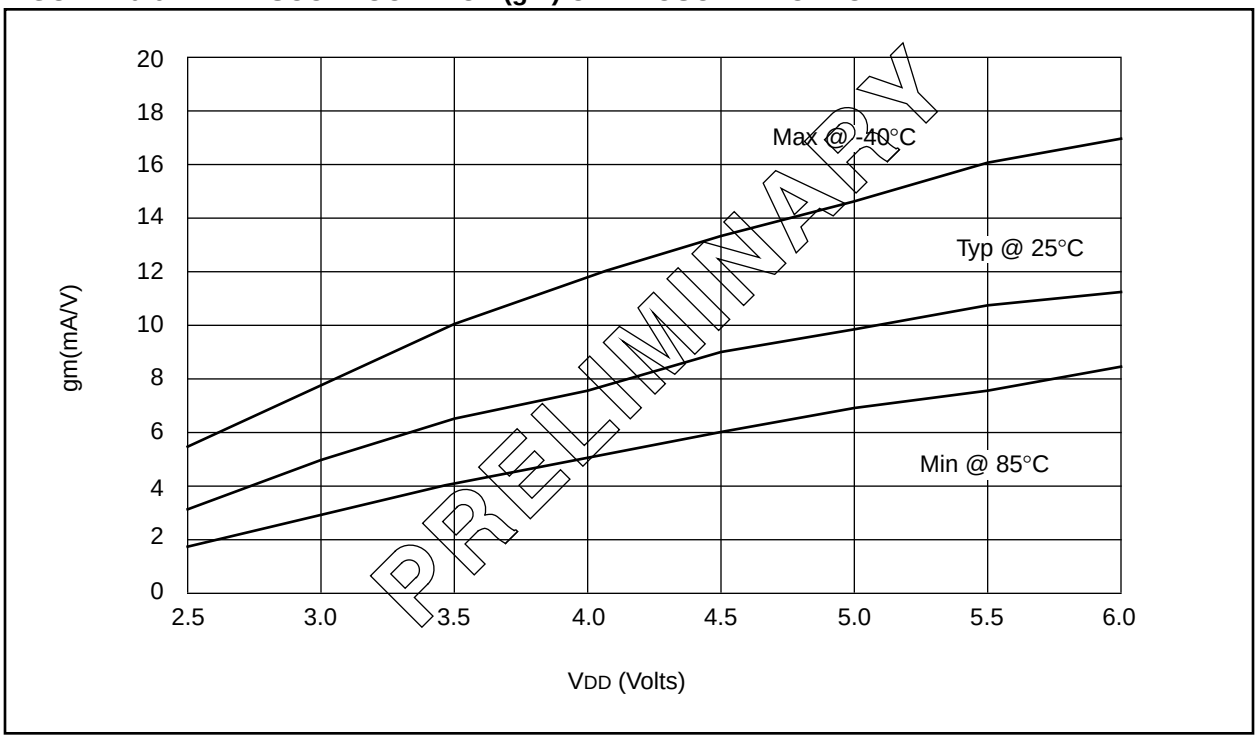


FIGURE 20-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-17: I_{OL} vs. V_{OL}, V_{DD} = 5V

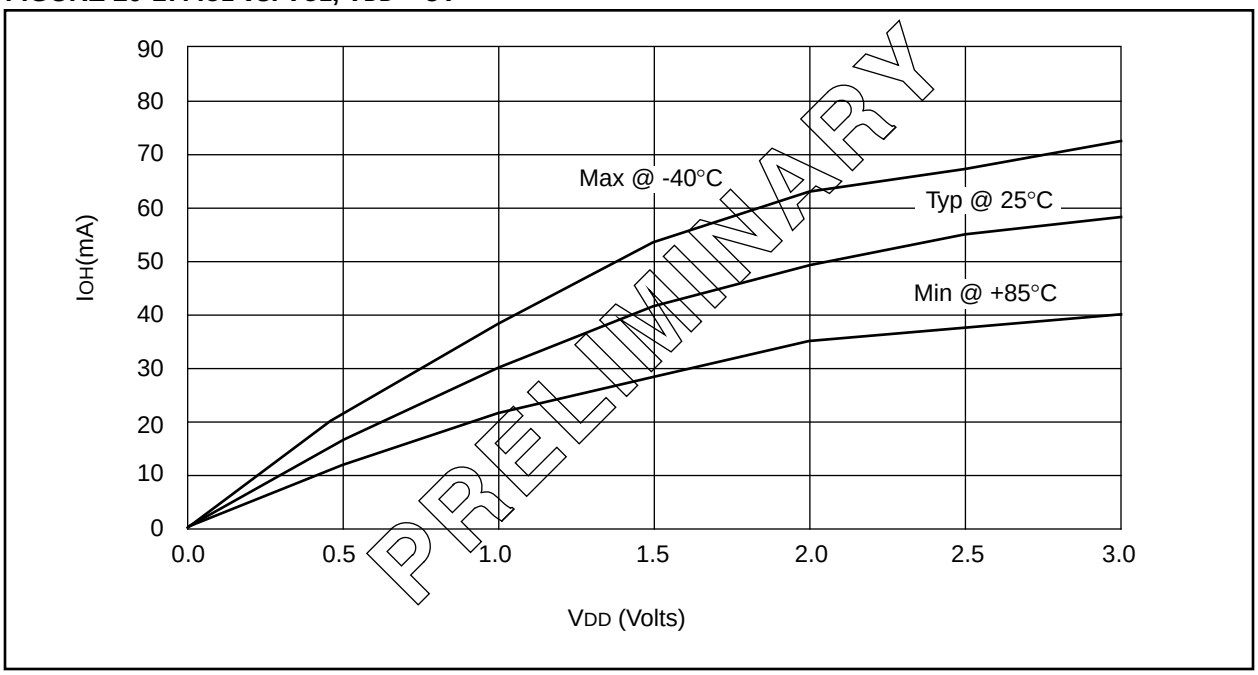
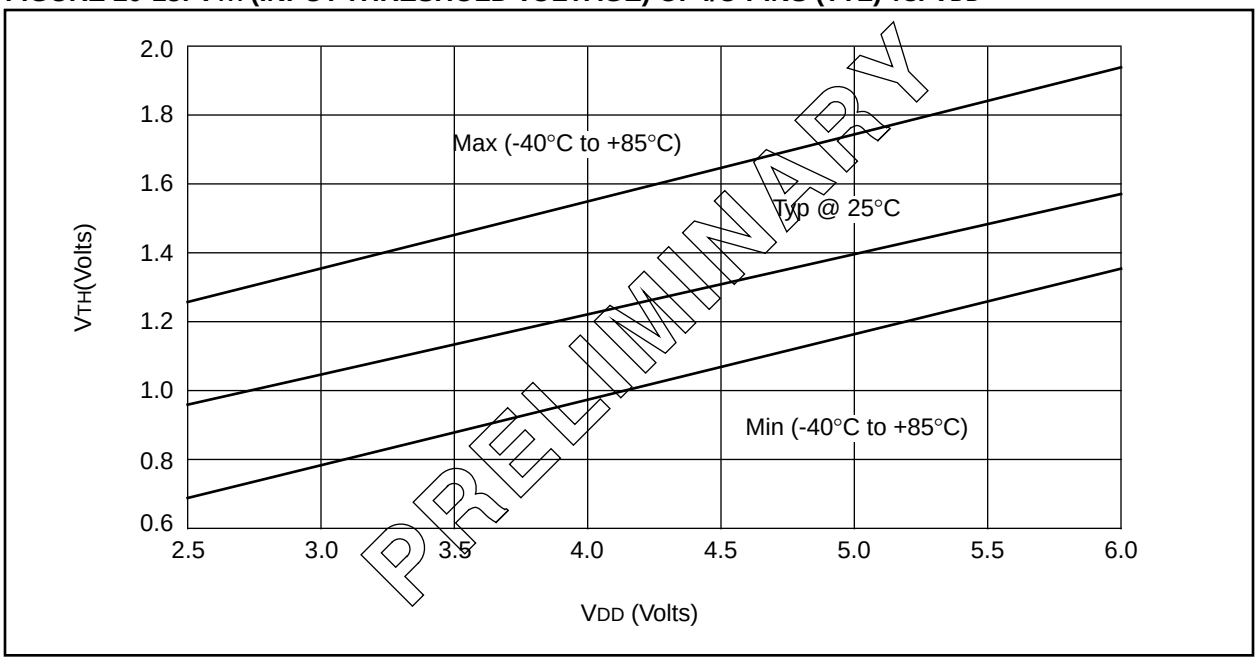


FIGURE 20-18: V_{TH} (INPUT THRESHOLD VOLTAGE) OF I/O PINS (TTL) vs. V_{DD}



E.2 PIC16C5X Family of Devices

	Clock	Memory				Peripherals		Features	
	Maximum Frequency of Operation (MHz)	Program Memory (x12 words)	EPROM	ROM	RAM Data Memory (bytes)	Timer Module(s)	I/O Pins	Voltage Range (Volts)	Number of Instructions	Packages
PIC16C52	4	384	—	25	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC
PIC16C54	20	512	—	25	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16C54A	20	512	—	25	TMR0	12	2.0-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16CR54A	20	—	512	25	TMR0	12	2.0-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16C55	20	512	—	24	TMR0	20	2.5-6.25	33	28-pin DIP, SOIC, SSOP
PIC16C56	20	1K	—	25	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16C57	20	2K	—	72	TMR0	20	2.5-6.25	33	28-pin DIP, SOIC, SSOP
PIC16CR57B	20	—	2K	72	TMR0	20	2.5-6.25	33	28-pin DIP, SOIC, SSOP
PIC16C58A	20	2K	—	73	TMR0	12	2.0-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16CR58A	20	—	2K	73	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-On Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

E.6 PIC16C8X Family of Devices

	Clock	Memory				Peripherals		Features		
	Maximum Frequency of Operation (MHz)	Program Memory	Flash	EEPROM	ROM	Data Memory (bytes)	Data EEPROM (bytes)	Timer Module(s)	Interrupt Sources	I/O Pins	Voltage Range (Volts)	Packages
PIC16C84	10	—	1K	—	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16F84(1)	10	1K	—	—	68	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16CR84(1)	10	—	—	1K	68	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16F83(1)	10	512	—	—	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16CR83(1)	10	—	—	512	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC

All PIC16/17 family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect, and high I/O current capability.

All PIC16C8X family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local sales office for availability of these devices.

NOTES: